

CLAIMS

What is claimed is:

1. A lead frame for an integrated circuit package comprising:
a composite lead frame of a plastic material having a portion thereof including an intrinsic conductive polymer.
2. The lead frame of claim 1, further comprising:
an adhesive located on a portion of said composite lead frame.
3. The lead frame of claim 1, wherein said intrinsic conductive polymer is a polyaniline.
4. The lead frame of claim 1, wherein said composite lead frame is transparent.
5. A circuit card comprising:
at least one electronic device;
a circuit card; and
at least one connector for attaching a portion of said at least one electronic device to a portion of said circuit card, said at least one electronic device comprising an integrated circuit die attached to a portion of a plastic lead frame, said plastic lead frame including an intrinsic conductive polymer.
6. The circuit card of claim 5, wherein said plastic lead frame further comprises a plastic lead frame structure coated with a conductive polymer.
7. The circuit card of claim 6, wherein said conductive polymer coating is selected from the group consisting of polyaniline.

8. The circuit card of claim 7, wherein said polyaniline coating is of a thickness between about 25 μm and about 75 μm .

9. The circuit card of claim 5, wherein said plastic lead frame is composite plastic formed of a conventional polymer intermixed with a conductive polymer.

10. A computer system comprising at least one circuit card, said at least one circuit card comprised of a plurality of electronic devices, at least one electronic device of said plurality comprising at least one integrated circuit die connected to a portion of a plastic lead frame including an intrinsic polymer material.

11. The computer system of claim 10, wherein said plastic lead frame further comprises a plastic lead frame structure coated with a conductive polymeric coating.

12. The computer system of claim 11, wherein said conductive polymeric coating is selected from the group consisting of polyaniline.

13. The computer system of claim 10, wherein said plastic lead frame is composite plastic formed of a conventional polymer intermixed with a conductive polymer.